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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



AN48820A

Low current consumption, high sensitivity CMOS Hall IC

Operate by the value of magnetic flux density, regardless of polarity

Overview

The AN48820A is a Hall IC (a magnetic sensor) which has 2 times or more sensitivity and a low current consumption of about one three-hundredth compared with our conventional one.

In this Hall IC, a Hall element, an offset cancel circuit, an amplifier circuit, a sample and hold circuit, a Schmitt circuit, and output stage FET are integrated on a single chip housed in a small package by IC technique.

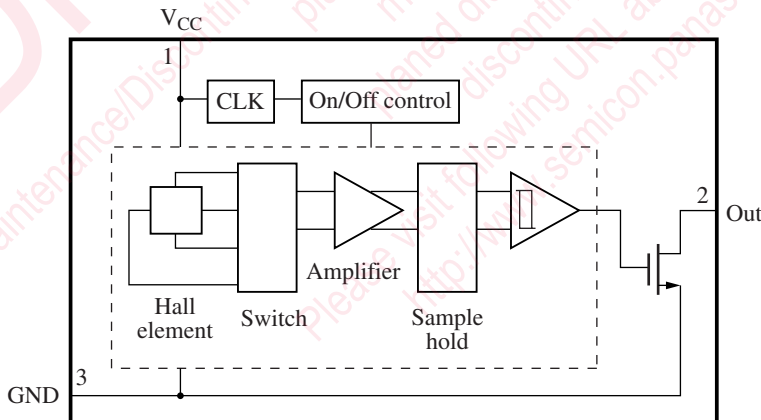
Features

- Either North nor South magnetic pole can be selected *
- High sensitivity (6 mT max.) due to offset cancel circuit and a new sample and hold circuit
- Small current by using intermittent action
(Average supply current: 3.5 μ A typ.)
- Small package (SMD)
- Open drain output

Applications

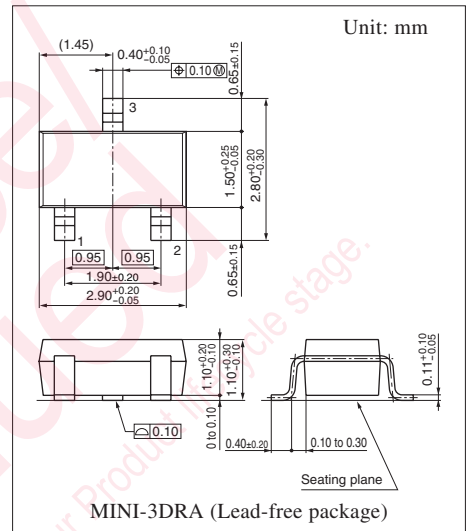
- Flip type cellular phone, digital video camera

Block Diagram



Pin Descriptions

Pin No.	Symbol	Description
1	V _{CC}	Power supply
2	Out	Output
3	GND	Ground

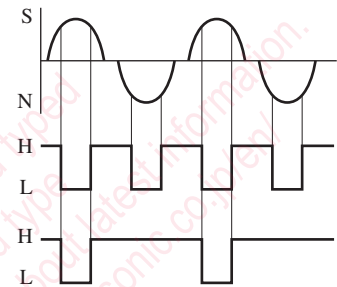


Note) *:

Magnetic flux density

AN48820A □ output level

Conventional model output level



■ Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V_{CC}	5	V
Output voltage	V_{OUT}	5	V
Supply current	I_{CC}	5	mA
Output current	I_{OUT}	15	mA
Power dissipation *1, 2	P_D	60	mW
Operating ambient temperature *1	T_{opr}	-25 to +75	°C
Storage temperature *1	T_{stg}	-55 to +125	°C

Note) *1: Except for the power dissipation, operating ambient temperature and storage temperature, all ratings are for $T_a = 25^\circ\text{C}$.

*2: $T_a = 85^\circ\text{C}$. For the independent IC without a heat sink. Please use within the range of power dissipation, referring to $P_D - T_a$ curve.

■ Recommended Operating Range

Parameter	Symbol	Range	Unit
Supply voltage	V_{CC}	2.5 to 3.5	V

■ Electrical Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Operating magnetic flux density 1	B_{H-LS}	$V_{CC} = 3\text{ V}$	—	—	6	mT
Operating magnetic flux density 2 *1	B_{H-LN}	$V_{CC} = 3\text{ V}$	-6	—	—	mT
Operating magnetic flux density 3 *2	B_{L-HS}	$V_{CC} = 3\text{ V}$	0.5	—	—	mT
Operating magnetic flux density 4 *2	B_{L-HN}	$V_{CC} = 3\text{ V}$	—	—	-0.5	mT
Output voltage 1	V_{OLS}	$V_{CC} = 3\text{ V}$, $I_O = 2\text{ mA}$, $B = 6.0\text{ mT}$	—	0.1	0.3	V
Output voltage 2	V_{OLN}	$V_{CC} = 3\text{ V}$, $I_O = 2\text{ mA}$, $B = -6.0\text{ mT}$	—	0.1	0.3	V
Output current 1	I_{OHS}	$V_{CC} = 3\text{ V}$, $V_O = 3\text{ V}$, $B = 0.5\text{ mT}$	—	—	10	μA
Output current 1	I_{OHN}	$V_{CC} = 3\text{ V}$, $V_O = 3\text{ V}$, $B = -0.5\text{ mT}$	—	—	10	μA
Supply current 1 *3	I_{CCAVE}	$V_{CC} = 3\text{ V}$, $B = 0.5\text{ mT}$	—	3.5	—	μA

Note) *1: Symbol B_{H-LS} , B_{H-LN} stands for the operating magnetic flux density where its output level varies from high to low.

*2: Symbol B_{L-HS} , B_{L-HN} stands for the operating magnetic flux density where its output level varies from low to high.

*3: $I_{CCAVE} = \{I_{CCON} \times t_{ON} + I_{CCOFF} \times t_{OFF}\} / \{t_{ON} + t_{OFF}\}$

• Design reference data

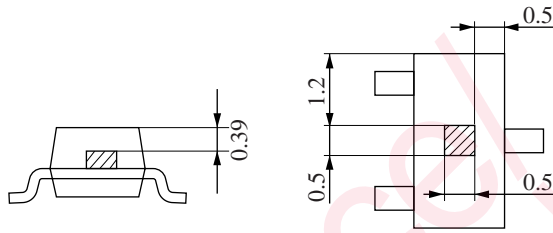
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Hysteresis width 1	BWS	$V_{CC} = 3\text{ V}$	—	1.2	—	mT
Hysteresis width 2	BWN	$V_{CC} = 3\text{ V}$	—	1.2	—	mT
Supply current 2	I_{CCON}	$V_{CC} = 3\text{ V}$, $B = 0.5\text{ mT}$	—	1.4	—	mA
Supply current 3	I_{CCOFF}	$V_{CC} = 3\text{ V}$, $B = 0.5\text{ mT}$	—	2	—	μA
Operating time	t_{ON}	$V_{CC} = 3\text{ V}$	—	40	—	μs
Stop time	t_{OFF}	$V_{CC} = 3\text{ V}$	—	41	—	ms

Note) It will operate normally in approximately 41 ms after power on.

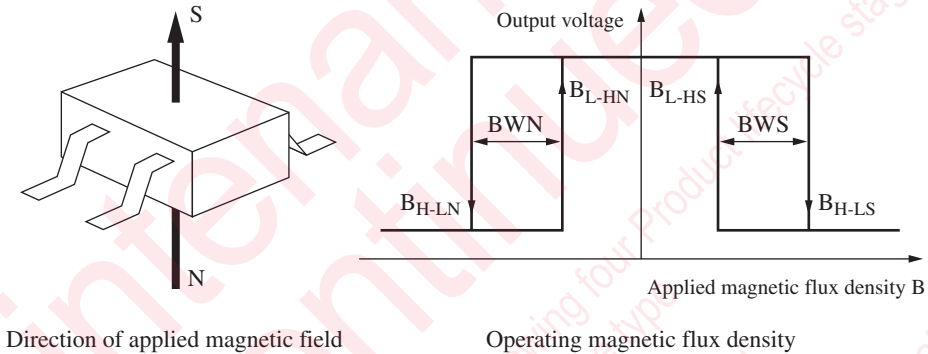
■ Technical Data

• Position of a Hall element (unit in mm)

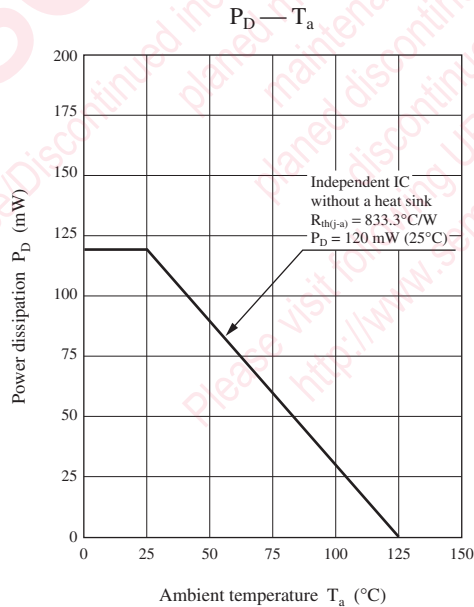
Distance from a package surface to sensor part: 0.39 mm (reference value)
 A Hall element is placed on the shaded part in the figure.



• Magneto-electro conversion characteristics



■ Power dissipation of package MINI-3DRA



■ Caution on Use of Hall ICs

The Hall ICs are often used to detect movement. In such cases, the position of the Hall IC may be changed by exposition to shock or vibration over a long period of time, and it causes the detection level change. To prevent this, fix the package with adhesives or fix it on a dedicated case.

1. A case using an adhesive

Some kinds of adhesive generate corrosive gas (such as chloric gas) during curing. This corrosive gas corrodes the aluminum on the surface of the Hall IC, and may cause a functional defect of disconnection.

If Hall IC is to be sealed after installation, attention should be given to the adhesive or resin used for peripherals and substrate cleaner, as well as to the adhesive used for Hall IC installation. Please confirm the above matter to those manufacturers before using.

We could not select the specified adhesive, for we find it difficult to guarantee the ingredient of each adhesive.

2. Power supply line/Power transmission line

If a power supply line/power transmission line becomes longer, noise and/or oscillation may be found on the line. In this case, set the capacitor of 0.1 μF to 10 μF near the Hall IC to prevent it.

If a voltage of 18 V or more is thought to be applied to the power supply line (flyback voltage from coil or the ignition pulse, etc.), avoid it with external components (capacitor, resistor, Zener diode, diode, surge absorbing elements, etc.).

3. On mounting of the surface mount type package (MINI-3DR)

When mounted on the printed circuit board, the Hall IC may be highly stressed by the warp that may occur from the soldering. This may also cause a change in the operating magnetic flux density and a deterioration of its resistance to moisture.



4. V_{CC} and GND

Do not reverse V_{CC} and GND. If the V_{CC} and GND pins are reversely connected, this IC will be destroyed. If the IC GND-pin voltage is set higher than other pin voltage, the IC configuration will become the same as a forward biased diode. Therefore, it will turn on at the diode forward voltage (approximately 0.7 V), and a large current will flow through the IC, ending up in its destruction. (This is common to monolithic IC.)

5. Cautions on power-on of Hall IC

When a Hall IC is turned on, the position of the magnet or looseness may change the output of a Hall IC, and a pulse may be generated. Therefore, care should be given whenever the output state of a Hall IC is critical when the supply power is on.

6. On using flux in soldering

Choose a flux which does not include ingredients from halogen group, such as chlorine, fluorine, etc. The ingredients of halogen group may enter where the lead frame and package resin joint, causing corrosion and the disconnection of the aluminum wiring on the surface of an IC chip.

7. On surface treatment of mini-mold package

Surface treatment is available in either smooth or dull finish.

8. On soldering of the surface mount type package

Surface mounting type Hall ICs are apt to change its electrical characteristics due to the stress from soldering at mounting. Therefore, avoid the mounting by flow (dipping) and a soldering iron. Please mount it by reflow soldering abiding by its recommended conditions.

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